

**METHOD FOR RECONSTRUCTING AN INTEGRATED CIRCUIT
PACKAGE USING LAPPING**

Inventors: Inventors: Joseph J. Dlugokecki , Gerardo Bagalawig
Nazareno, Carmencita I. Robbins, Steven David Swendrowski

ABSTRACT

A method is provided for reconstructing an integrated circuit package
5 comprising: attaching a die to exposed wire bond pads of a lead frame so that the
die is electrically connected to the lead frame; and encapsulating the die and the
wire bond pads in an encapsulant; and reshaping an upper surface of the
encapsulant where at least a portion of the encapsulant reshaping is performed by a
lapping process.

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